AMPMODU | OEG Miniature Relay PCF

TE Internal #: 829309-8

TE Internal Description: 2X 8P MOD2 STIFTLEI

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Type: PCB Mount Header

Connector System: Board-to-Board

Number of Positions: 16

Number of Rows: 2

Centerline (Pitch): 2.54 mm [.1 in]

Features

Product Type Features

PCB Connector Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Stackable	Yes
Number of Positions	16
Number of Rows	2
PCB Mount Orientation	Vertical
Board-to-Board Configuration	Parallel

Body Features

Primary Product Color	Green
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Contact Features

Contact Shape & Form	Square
Contact Underplating Material	Nickel
Contact Base Material	Copper Zinc
Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Mating Area Plating Material Thickness	.8 μm[31.5 μin]



Contact Mating Area Plating Material	Gold (Au), Gold Flash
Contact Type	Pin
Contact Current Rating (Max)	5 A
Termination Features	
Termination Method to PCB	Through Hole - Solder
Mechanical Attachment	
Connector Mounting Type	Board Mount
Mating Alignment	Without
PCB Mount Alignment	Without
PCB Mount Retention	Without
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	PBT
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	15.3 mm[.6 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Operation/Application	
Circuit Application	Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Method	Box

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2023 (233)



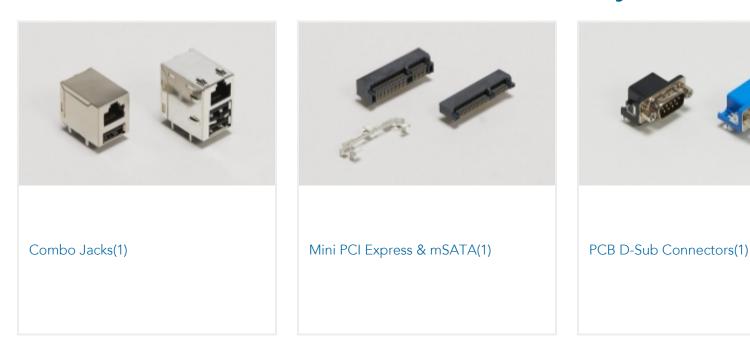
Does not contain REACH SVHC

Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

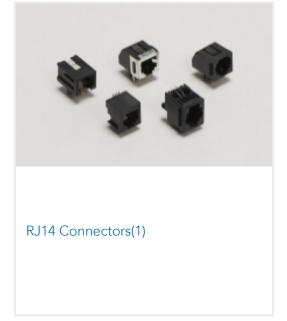
Product Compliance Disclaimer

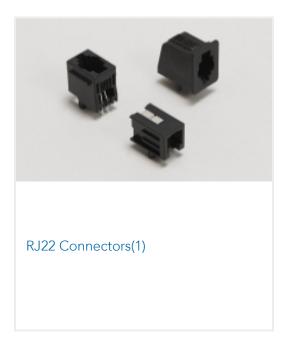
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Also in the Series | OEG Miniature Relay PCF









Customers Also Bought









Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_829309-8_E.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_829309-8_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_829309-8_E.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Agency Approvals

UL Report

English